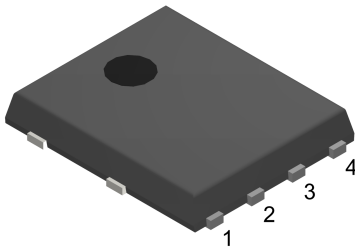
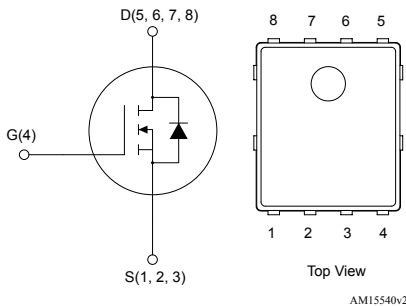


N-channel 60 V, 2.4 mΩ typ., 140 A, STripFET F7 Power MOSFET in a PowerFLAT 5x6 package



PowerFLAT™ 5x6



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STL140N6F7	60 V	2.8 mΩ	140 A	125 W

- Among the lowest R_{DS(on)} on the market
- Excellent FoM (figure of merit)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness
- Logic level V_{GS(th)}

Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.



Product status

STL140N6F7

Product summary

Order code	STL140N6F7
Marking	140N6F7
Package	PowerFLAT 5x6
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_{case} = 25\text{ }^{\circ}\text{C}$	140	A
	Drain current (continuous) at $T_{case} = 100\text{ }^{\circ}\text{C}$	107	
$I_{DM}^{(1)(2)}$	Drain current (pulsed)	560	A
$I_D^{(3)}$	Drain current (continuous) at $T_{pcb} = 25\text{ }^{\circ}\text{C}$	30	A
	Drain current (continuous) at $T_{pcb} = 100\text{ }^{\circ}\text{C}$	21	
$I_{DM}^{(2)(3)}$	Drain current (pulsed)	116	A
$P_{TOT}^{(1)}$	Total power dissipation at $T_{case} = 25\text{ }^{\circ}\text{C}$	125	W
$P_{TOT}^{(3)}$	Total power dissipation at $T_{pcb} = 25\text{ }^{\circ}\text{C}$	4.8	W
$E_{AS}^{(4)}$	Single pulse avalanche energy	38	mJ
T_{stg}	Storage temperature range	-55 to 175	$^{\circ}\text{C}$
T_j	Operating junction temperature range		

1. This value is rated according to R_{thj-c} .
2. Pulse width is limited by safe operating area.
3. This value is rated according to $R_{thj-pcb}$.
4. Starting $T_j = 25\text{ }^{\circ}\text{C}$, $I_D = 16\text{ A}$, $V_{DD} = 40\text{ V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	31.3	$^{\circ}\text{C/W}$
$R_{thj-case}$	Thermal resistance junction-case	1.2	

1. When mounted on a 1-inch² FR-4 board, 2oz Cu, $t < 10\text{ s}$

2 Electrical characteristics

($T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 3. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$, $I_{\text{D}} = 1\text{ mA}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 60\text{ V}$			1	μA
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$, $V_{\text{GS}} = \pm 20\text{ V}$			100	nA
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_{\text{D}} = 250\text{ }\mu\text{A}$	2		4	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$, $I_{\text{D}} = 15\text{ A}$		2.4	2.8	m Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{\text{DS}} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{\text{GS}} = 0\text{ V}$	-	3110	-	pF
C_{oss}	Output capacitance		-	1520	-	
C_{rss}	Reverse transfer capacitance		-	193	-	
Q_{g}	Total gate charge	$V_{\text{DD}} = 30\text{ V}$, $I_{\text{D}} = 30\text{ A}$, $V_{\text{GS}} = 0\text{ to }10\text{ V}$ (see Figure 13. Test circuit for gate charge behavior)	-	55	-	nC
Q_{gs}	Gate-source charge		-	19	-	
Q_{gd}	Gate-drain charge		-	18	-	

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 30\text{ V}$, $I_{\text{D}} = 15\text{ A}$, $R_{\text{G}} = 4.7\text{ }\Omega$, $V_{\text{GS}} = 10\text{ V}$ (see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	24	-	ns
t_{r}	Rise time		-	68	-	
$t_{\text{d(off)}}$	Turn-off delay time		-	39	-	
t_{f}	Fall time		-	20	-	

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{\text{SD}}^{(1)}$	Forward on voltage	$V_{\text{GS}} = 0\text{ V}$, $I_{\text{SD}} = 30\text{ A}$	-		1.2	V
t_{rr}	Reverse recovery time	$I_{\text{SD}} = 30\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{\text{DD}} = 48\text{ V}$ (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	42.4		ns
Q_{rr}	Reverse recovery charge		-	38.2		nC
I_{RRM}	Reverse recovery current		-	1.8		A

1. Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

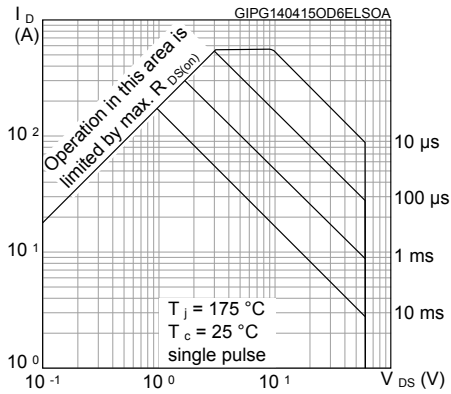


Figure 2. Thermal impedance

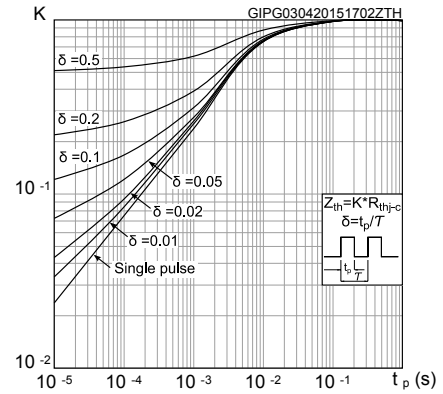


Figure 3. Output characteristics

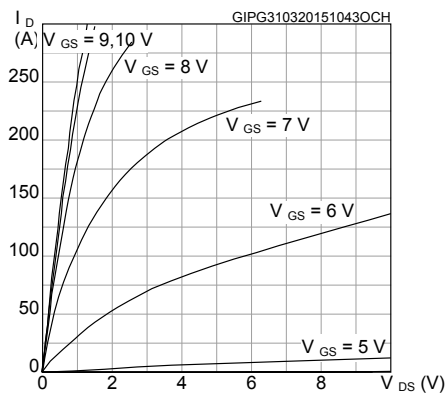


Figure 4. Transfer characteristics

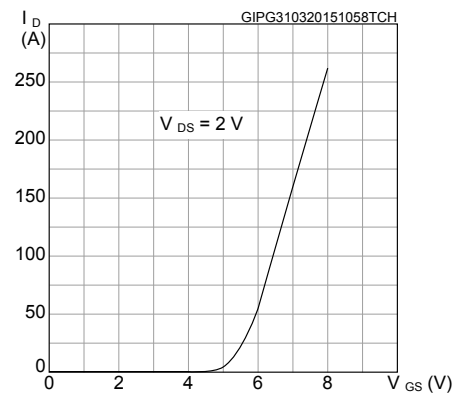


Figure 5. Gate charge vs gate-source voltage

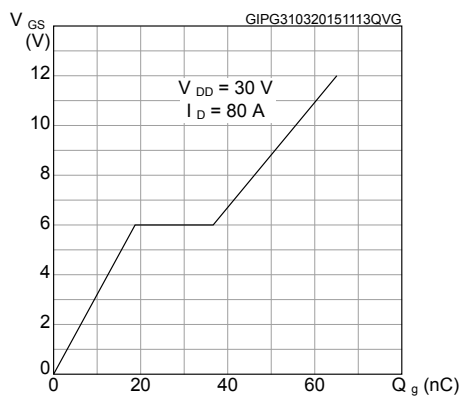


Figure 6. Static drain-source on-resistance

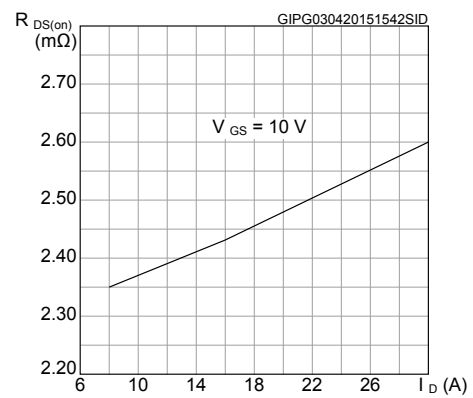
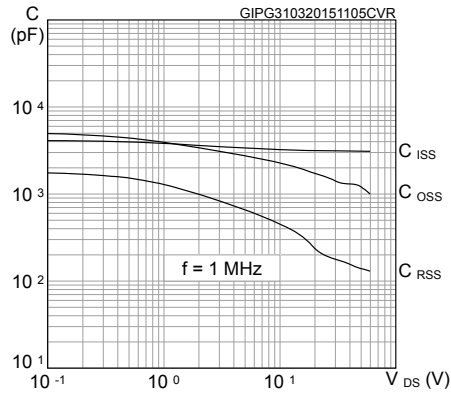
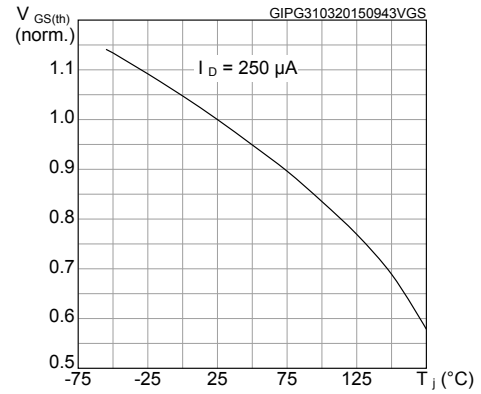
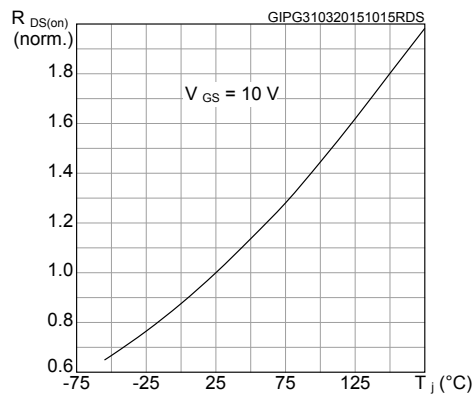
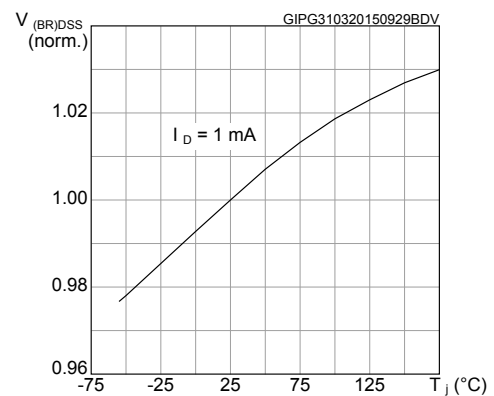
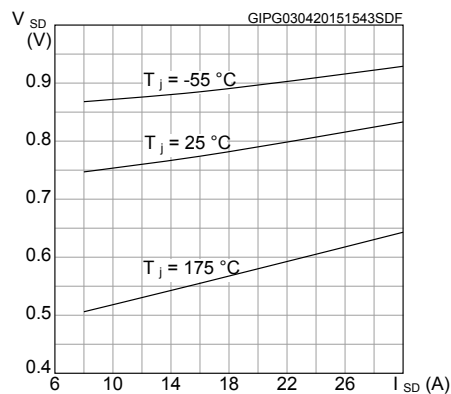
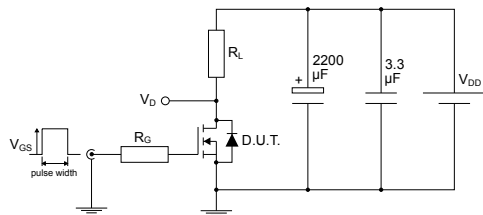
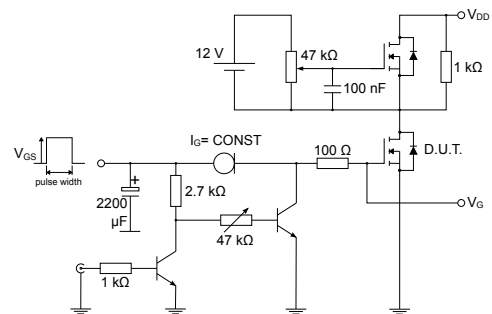


Figure 7. Capacitance variations

Figure 8. Normalized gate threshold voltage vs temperature

Figure 9. Normalized on-resistance vs temperature

Figure 10. Normalized $V_{(BR)DSS}$ vs temperature

Figure 11. Source-drain diode forward characteristics


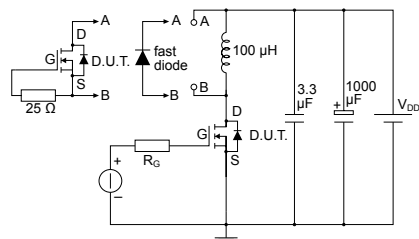
3 Test circuits

Figure 12. Test circuit for resistive load switching times


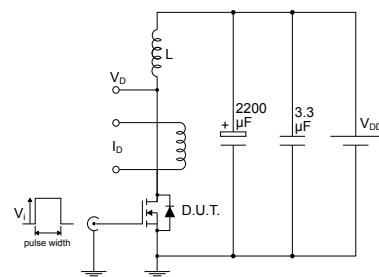
AM01468v1

Figure 13. Test circuit for gate charge behavior


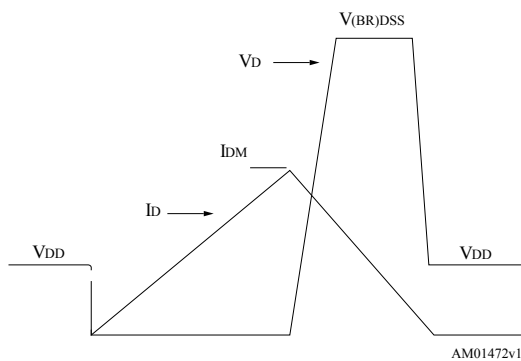
AM01469v1

Figure 14. Test circuit for inductive load switching and diode recovery times


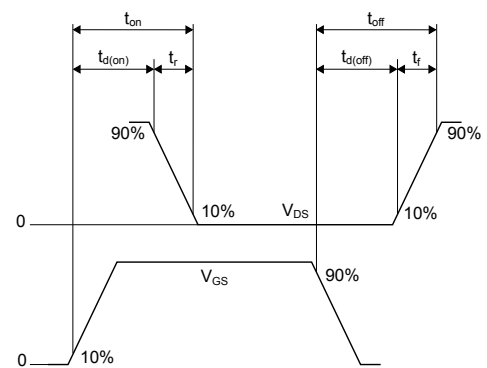
AM01470v1

Figure 15. Unclamped inductive load test circuit


AM01471v1

Figure 16. Unclamped inductive waveform


AM01472v1

Figure 17. Switching time waveform


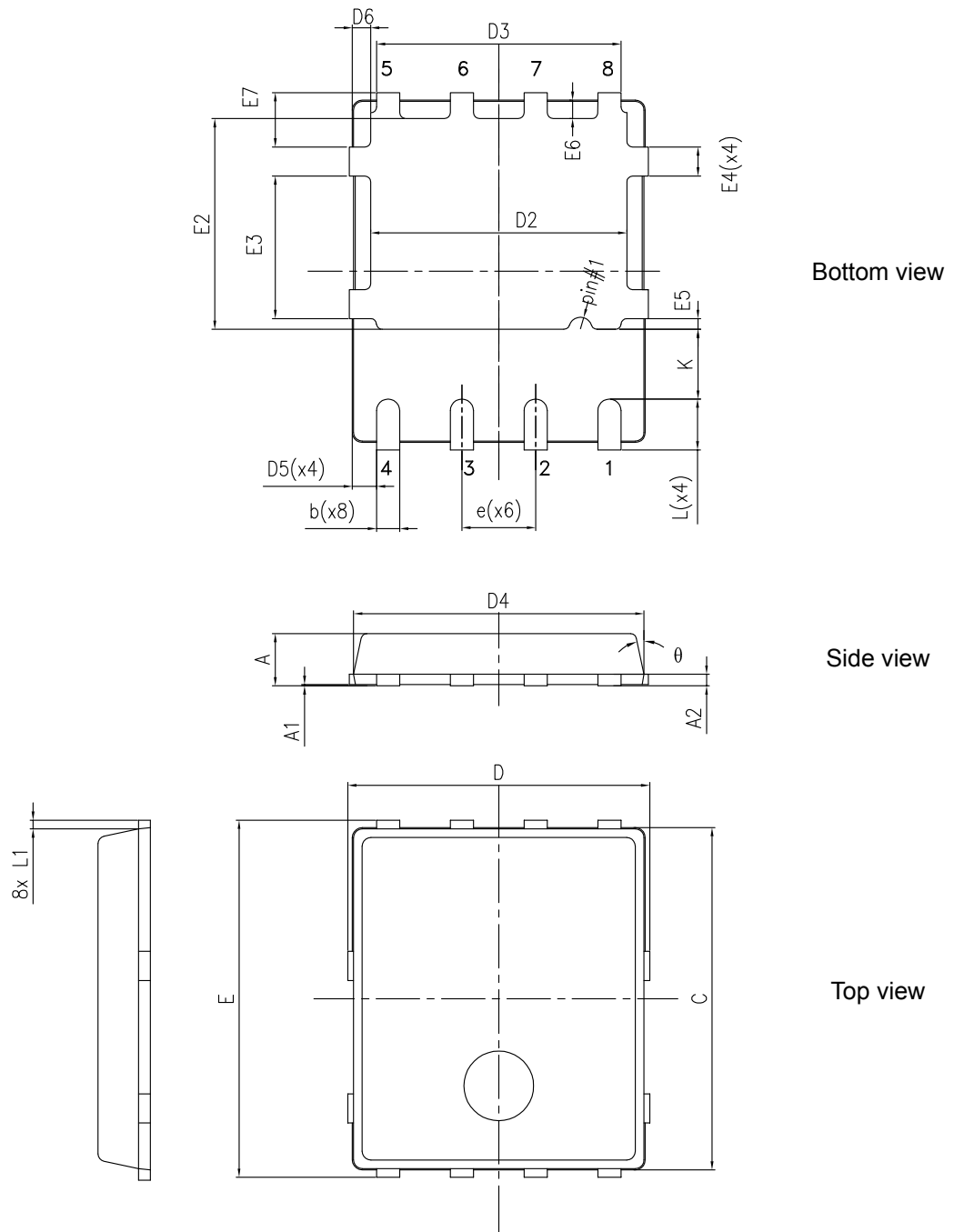
AM01473v1

4 **Package information**

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 PowerFLAT 5x6 type C package information

Figure 18. PowerFLAT 5x6 type C package outline



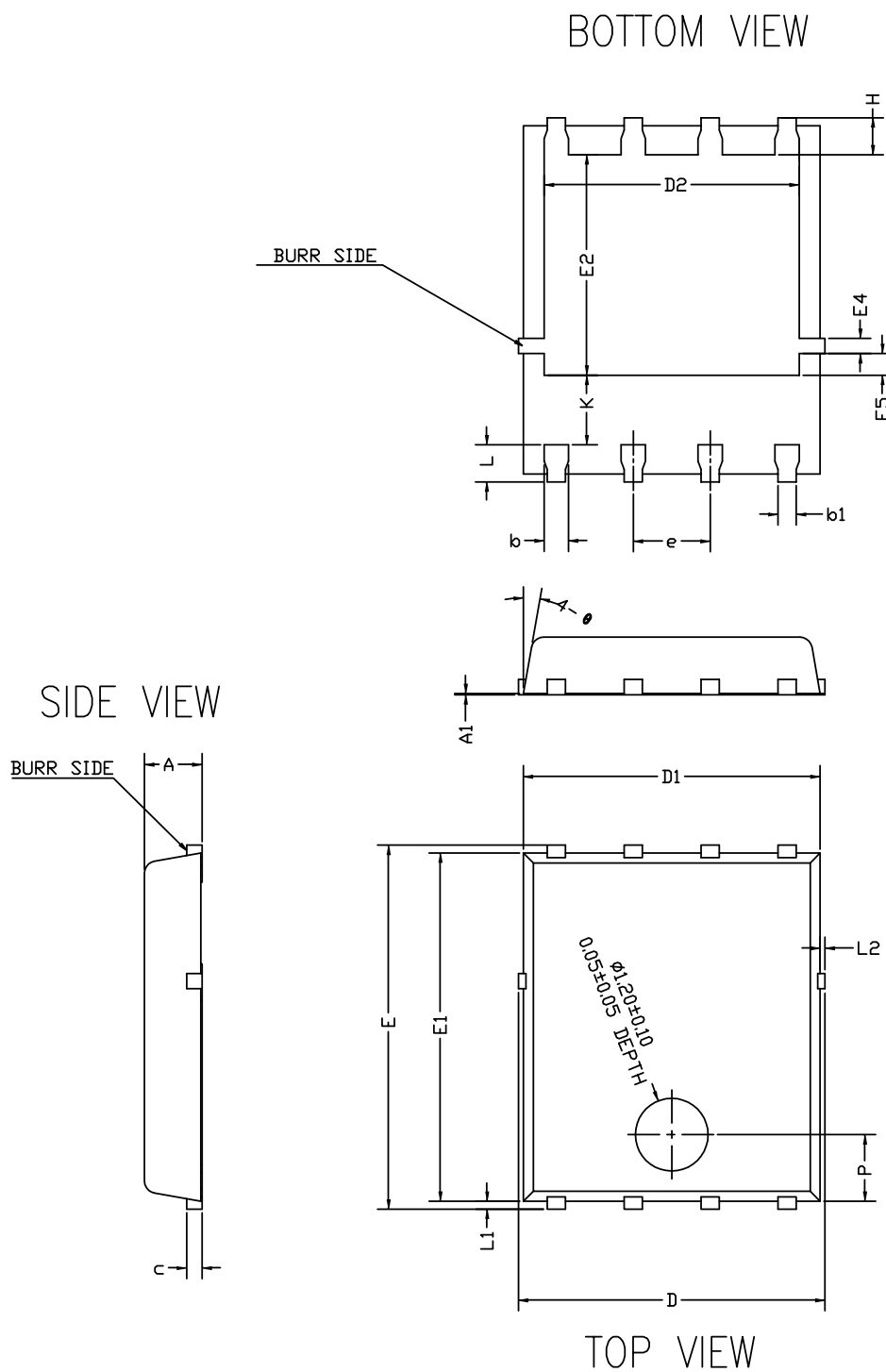
8231817_typeC_Rev18

Table 7. PowerFLAT 5x6 type C package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.20
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	5.95	6.15	6.35
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.75	0.90	1.05
K	1.05		1.35
L	0.725		1.025
L1	0.05	0.15	0.25
θ	0°		12°

4.2 PowerFLAT 5x6 type SUBCON package information

Figure 19. PowerFLAT 5x6 type SUBCON package outline

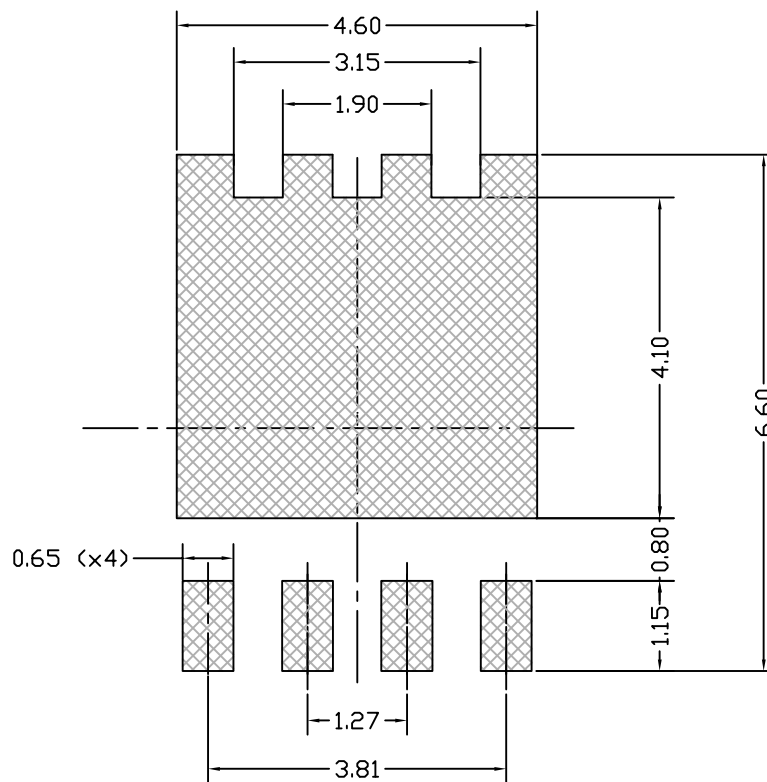


8231817_SUBCON_REV4

Table 8. PowerFLAT 5x6 type SUBCON package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.90	0.95	1.00
A1		0.02	
b	0.35	0.40	0.45
b1		0.30	
c	0.21	0.25	0.34
D	4.80		5.10
D1	4.80	4.90	5.00
D2	4.01	4.21	4.31
e	1.17	1.27	1.37
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.54	3.64	3.74
E4	0.15	0.25	0.35
E5	0.26	0.36	0.46
H	0.51	0.61	0.71
K	0.95		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
L2			0.10
P	1.00	1.10	1.20
θ	8°	10°	12°

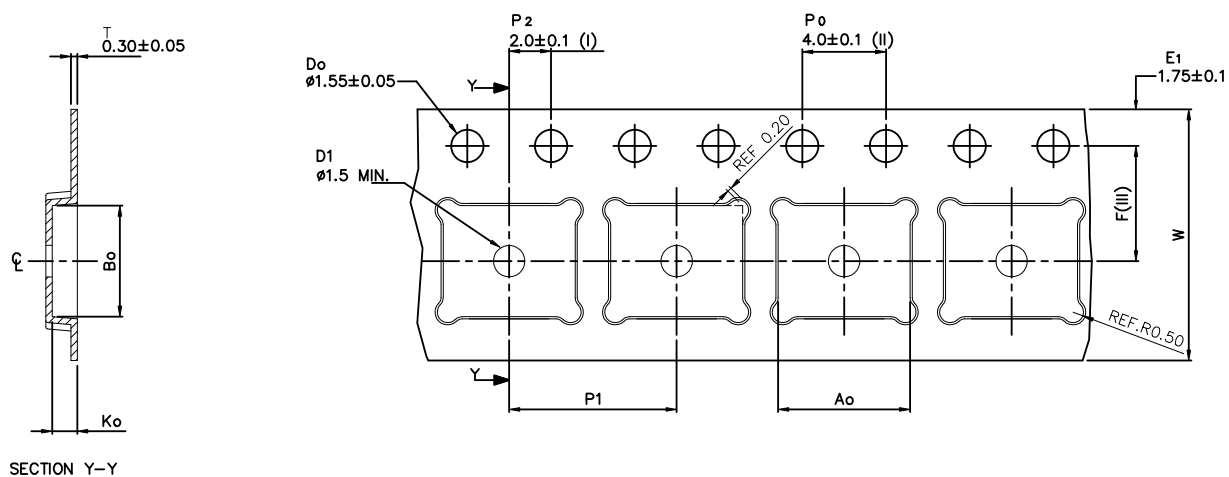
Figure 20. PowerFLAT 5x6 recommended footprint (dimensions are in mm)



8231817_FOOTPRINT_simp_Rev_18

4.3 PowerFLAT 5x6 packing information

Figure 21. PowerFLAT 5x6 tape (dimensions are in mm)



Ao	6.30 +/– 0.1
Bo	5.30 +/– 0.1
Ko	1.20 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

(I) Measured from centreline of sprocket hole to centreline of pocket.

(II) Cumulative tolerance of 10 sprocket holes is ± 0.20 .

(III) Measured from centreline of sprocket hole to centreline of pocket

Base and bulk quantity 3000 pcs
 All dimensions are in millimeters

8234350_Tape_rev_C

Figure 22. PowerFLAT 5x6 package orientation in carrier tape

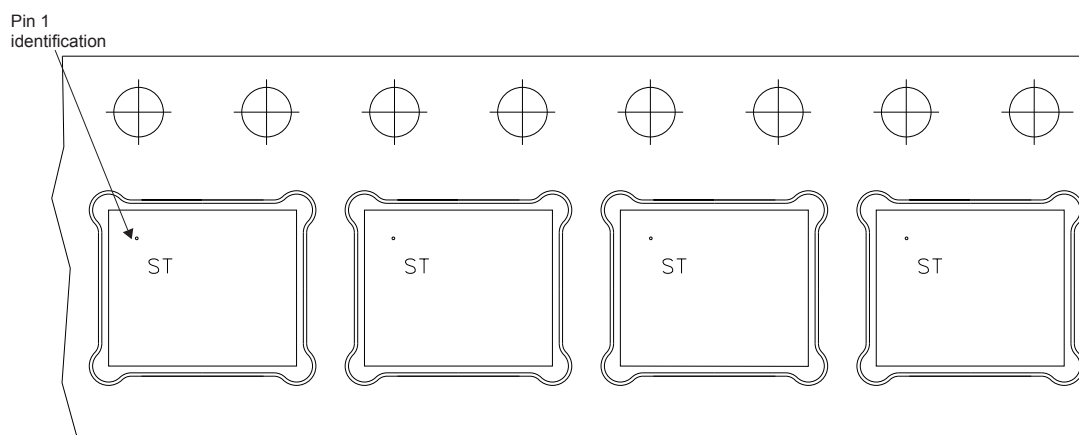
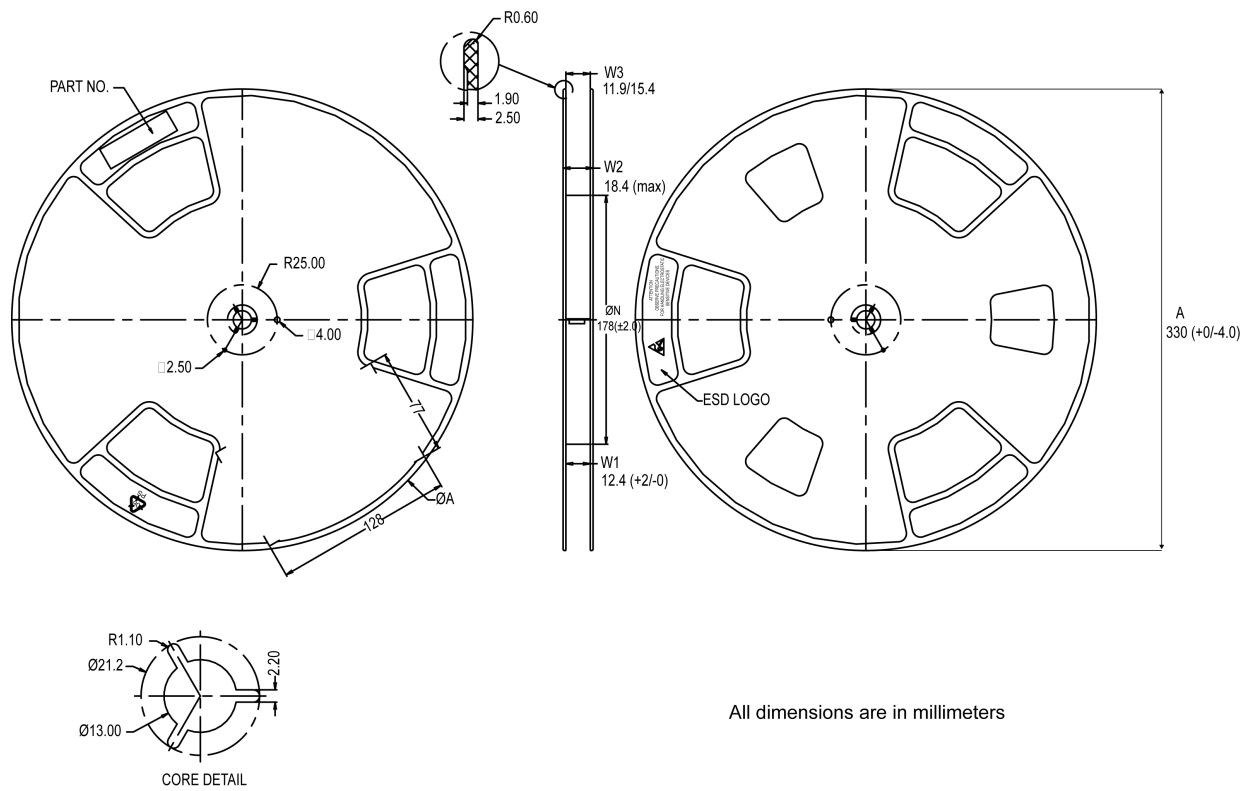


Figure 23. PowerFLAT 5x6 reel



All dimensions are in millimeters

8234350_Reel_rev_C

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Revision history

Table 9. Document revision history

Date	Revision	Changes
02-Aug-2013	1	First release.
18-Mar-2014	2	Updated V_{DS} value in <i>Table 2: Absolute maximum ratings</i> and <i>Table 4: On /off states</i> . Updated <i>Section 4: Package mechanical data</i> . Minor text changes.
09-Apr-2015	3	Text edits and formatting changes throughout document On cover page: -updated title description -updated device 'Features' and 'Description' Updated <i>section 1 Electrical ratings</i> Updated <i>section 2 Electrical characteristics</i> Added <i>section 2.1 Electrical characteristics (curves)</i> Updated and renamed <i>Section 4 Package information</i> (was <i>Package mechanical data</i>) Updated and renamed <i>Section 4.2 Packing information</i> (was <i>Section 5 Packaging mechanical data</i>)
19-May-2015	4	In <i>Section 2.1 Electrical characteristics (curves)</i> : - Updated <i>Figure 24: Capacitance variations</i>
21-Apr-2017	5	Added E_{AS} in <i>Table 2: "Absolute maximum ratings"</i> Updated <i>Section 4.1: "PowerFLAT™ 5x6 type C package information"</i> Minor text changes.
10-Sep-2019	6	Added: <i>Section 4.2 PowerFLAT 5x6 type SUBCON package information</i> . Minor text changes.
01-Oct-2019	7	Updated Section 4.2 PowerFLAT 5x6 type SUBCON package information . Minor text changes

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